DOCUMENT CHANGE REQUEST

DCR number 730
Changes required for: General
Originator: Petra Pribanova
Date: 2013/09/20
Date sent: 2012/05/30
Organisation: AVX Czech Republic
Status: IMPLEMENTED

Title:	Requirements for Lead Materials and Finishes for Components for Space Application		
Number:	23500	Issue:	5

Other documents affected:

Page:

6,7-8

Paragraph:

3.2 Approved lead and terminal material
3.3 Final finish

Original wording:

3.2 Approved lead and terminal material
Copper Alloy >97% Cu (Alloy K50 or K65)
3.3 Final finish
No modification, new final finish type only

Proposed wording:

3.2 Approved lead and terminal material
Copper Alloy >97% Cu (Alloy K50 or K65 or K88 or KHP194)
3.3 New Final finish types:
Type 1:
Reflowed Tin/Lead plating, with Nickel and Silver underplating.
Surface finish on active soldering surface:
The first layer shall be 0,05-1 um of electro-deposited nickel.
The second layer shall be 0,05-1 um of electro-deposited silver.
The final layer shall be reflowed electro-deposit tin-lead plating with a composition of 85-95 % tin (remainder lead).
The thickness of the tin-lead plating shall be u3,0-8,5 m.

Type 2:
Reflowed Tin/Lead plating, with Nickel and Silver underplating.
Surface finish on active soldering surface:
The first layer shall be 0,05-1 um of electro-deposited nickel.
The second layer shall be 0,05-1 um of electro-deposited silver.
The final layer shall be reflowed electro-deposit tin-lead plating with a composition of 85-95 % tin (remainder lead).
The thickness of the tin-lead plating shall be 4,5-10 um.

Justification:

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The termination material and plating have been validated through initial qualification of TAJ, MOQ of TAJ and TES evaluation (mountability testing) and that as far as you know there is no complain from user regarding to the mounting process.

Attachments:

N/A

Modifications:

As per PSWG No 59 (27/6/2013) dispositions recorded in ESCC 23500, draft issue 6 of June: ref doc. ESCC 25500 added, tin lead control plan requested, finish Numbers 16, 17, 18 added.

Approval signature:

Date signed:

2013-09-20